



# SOT732-1

metal flip chip package; 2 leads; 35 mm wide tape

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	FCP2
<b>Package type industry code</b>	FCP2
<b>Package style descriptive code</b>	FCP (flip chip package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	M (metal)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-3-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.95	-	35	35.05	mm
E	package width	[tbd]	-	1.3	[tbd]	mm
A	seated height	0.25	-	0.285	0.32	mm
A <sub>2</sub>	package height	[tbd]	-	0.085	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	2	-	



## 2. Package outline

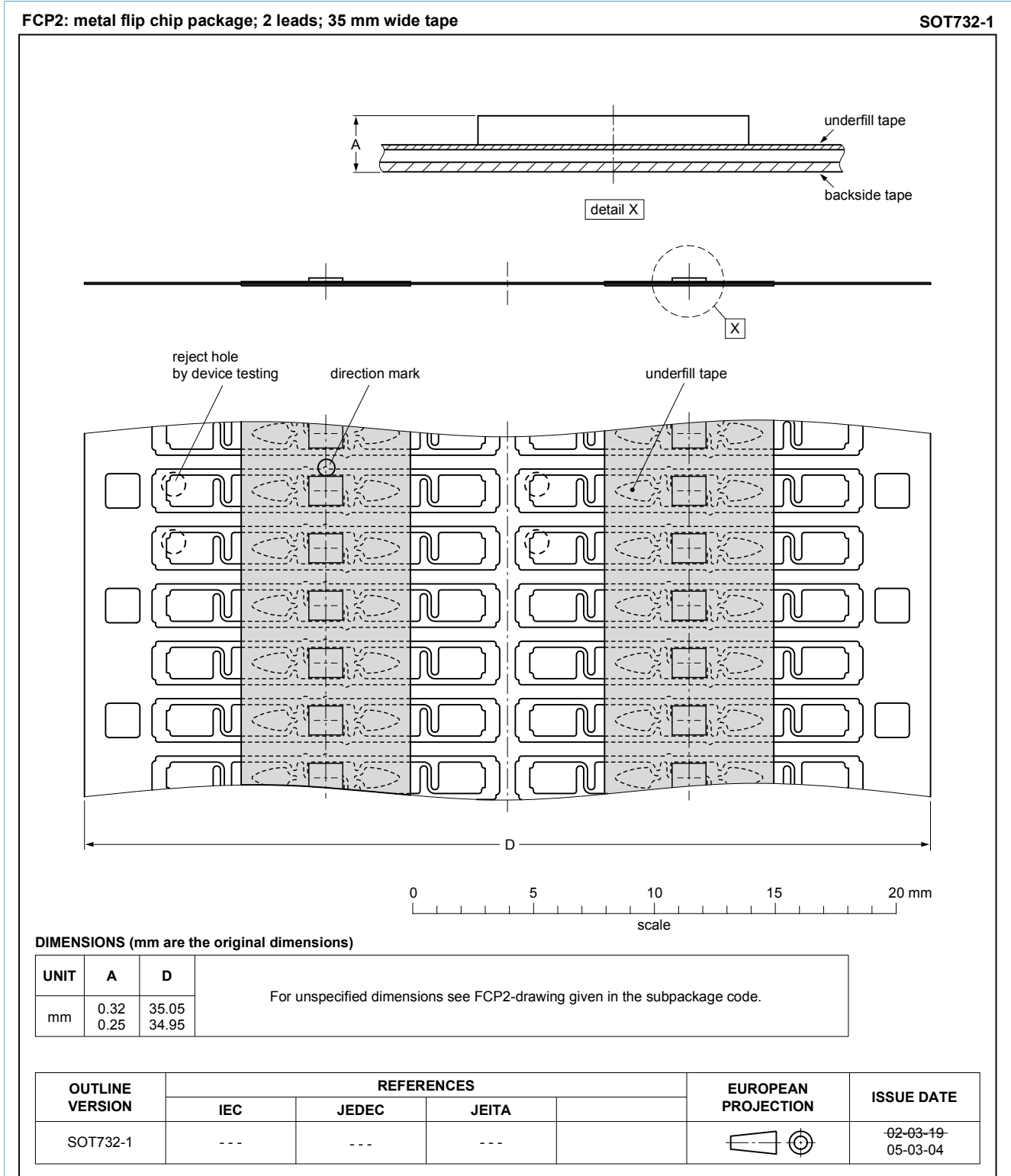


Fig. 1. Package outline FCP2 (SOT732-1)

### 3. Legal information

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